3D WARPAGE & RELIABILITY SIMULATION SERVICE

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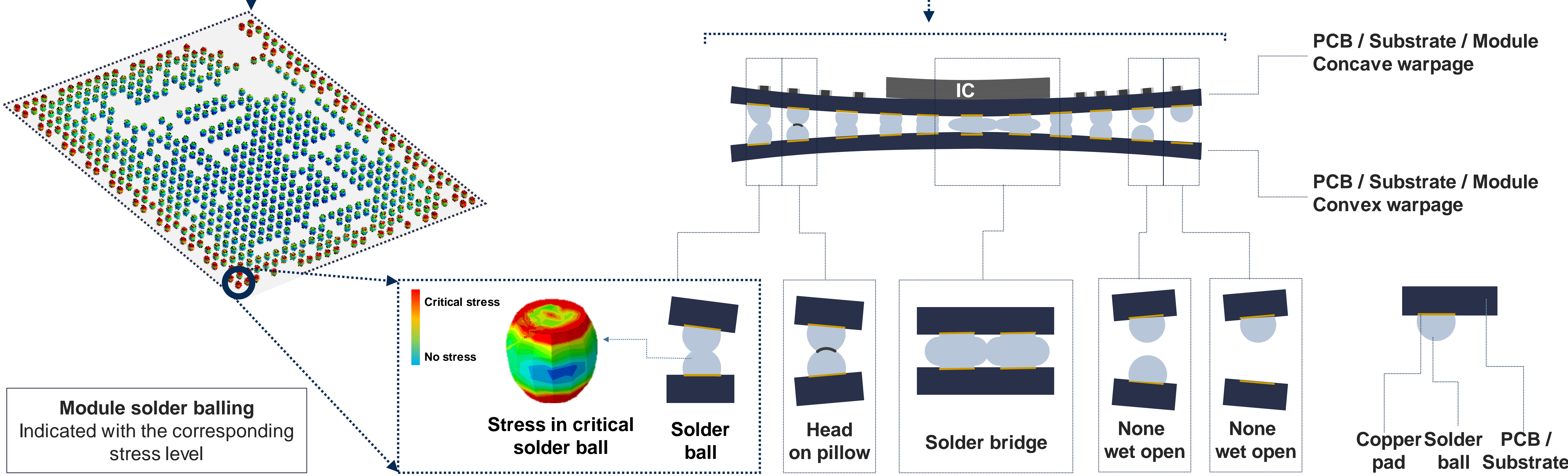


ISSUE

Assembly, asymmetric layer construction, incorrect core, prepreg, copper distribution or materials can result in warpage or reliability issues.

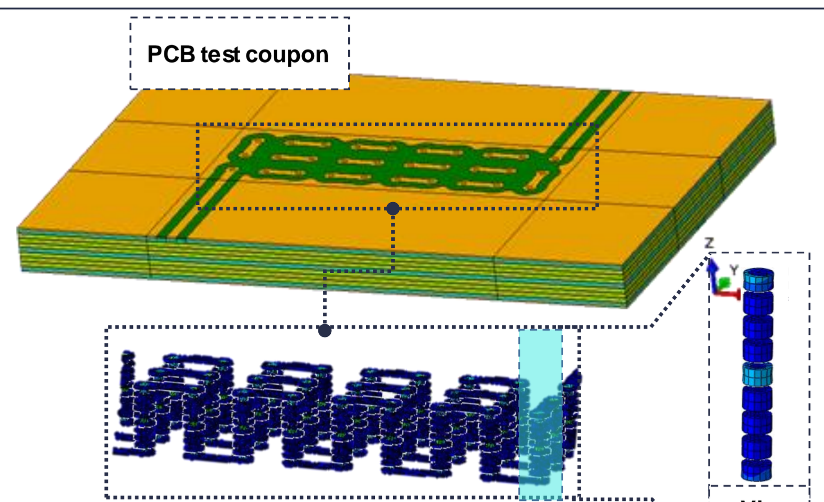
3D MATERIAL CHARACTERIZATION

AT&S has industry-leading 3D material characterization and modeling capabilities.

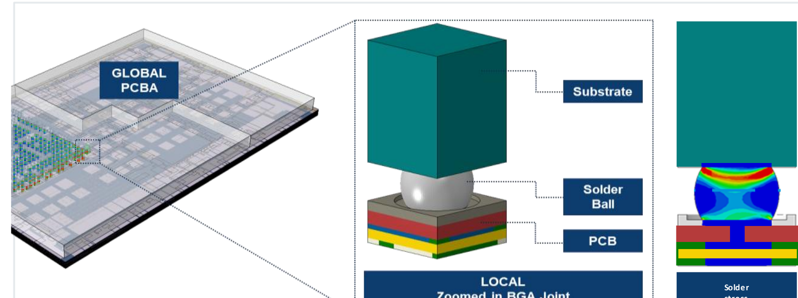
3D WARPAGE & RELIABILITY SIMULATION

With the support of the AT&S warpage & reliability simulation services issues in the assembly yield, reliability or even their statistical failure rate and life time predictions can be done in advance.

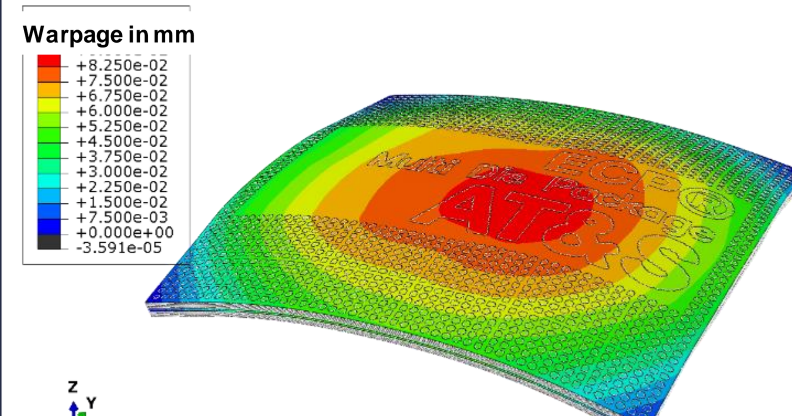
RELIABILITY SIMULATION		WARPAGE SIMULATION	
COPPER	SOLDER	CARD (PCB)	ASSEMBLED SYSTEM (PCBA)
Prediction of the stress & statistical failure rates of copper structures such as Vias or traces.	Prediction of the stress & statistical failure rates of solder joints.	Prediction of the bare PCB warpage and identifying the key drivers.	Prediction of the fully assembled PCB warpage and identifying the key drivers.



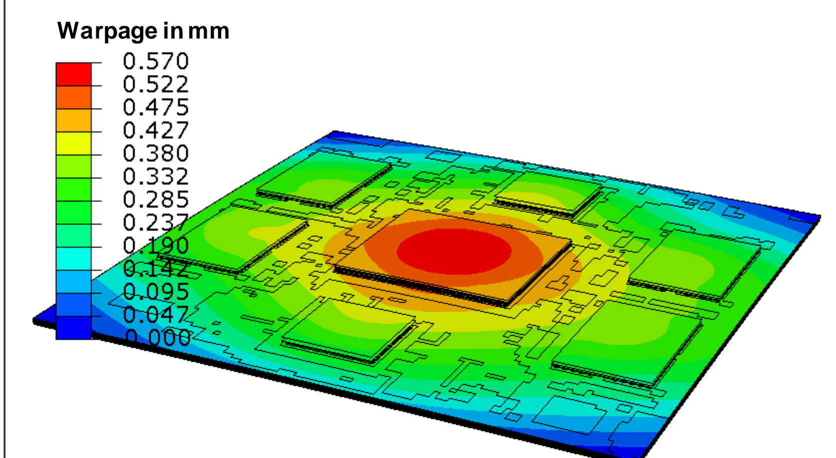
Reliability and stress prediction of an Via stack.



Reliability and stress prediction of solder joint connections on an module



Warpage simulation of a PCB with embedded components



Warpage simulation of a fully assembled PCB